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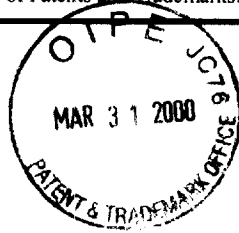
DOCKET NO.: 2336-028A

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of conveying party(ies):

- 1) Dong SHIN
- 2) Keon Yang PARK
- 3) Young Hwan SHIN



2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRO-MECHANICS CO., LTD.

Internal Address:

3-31-02

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Street Address:

314, Maetan-Dong, Paldal-ku, Suwon-si
Kyongki-Do, REPUBLIC OF KOREA

City: _____ State/Country: _____ ZIP: _____

Execution Date: February 21, 2000

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s).

09/467,780 filed December 20, 1999

B. Patent No(s).

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: LOWE HAUPTMAN GOPSTEIN GILMAN & BERNER

Internal Address:

Street Address: 1700 Diagonal Road, Suite 310

City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Benjamin J. Hauptman Reg. No. 29,310
Name and Registration No. of Person Signing

Signature

March 31, 2000
Date

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Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

PATENT
REEL: 010717 FRAME: 0841

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) Dong SHIN
- (2) Keon Yang PARK
- (3) Young Hwan SHIN

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.
314, Maetan-Dong, Paldal-ku, Suwon-si
Kyongki-Do, REPUBLIC OF KOREA

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD FOR MANUFACTURING BUILD-UP MULTI-LAYER PRINTED CIRCUIT BOARD BY USING YAG LASER

(a) for which an application for United States Letters Patent was filed on **December 20, 1999**, and identified by United States Serial No. **09/467,780**; or

(b) for which an application for United States Letters Patent was executed on ,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

DATE SIGNED

Name:

1) Dong SHIN

Name:

2) Keon Yang PARK

Name:

3) Young Hwan SHIN

Name:

Feb. 21, 2000

Feb. 21, 2000

Feb. 21, 2000